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Dated: May 27, 2008

Signature: \_\_\_\_\_

(Aaron M. Peters)

Docket No.: 29347/990488  
(PATENT)

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Patent Application of:  
Gi-Young JEUN et al.

Application No.: 09/677,558

Confirmation No.: 1618

Filed: September 29, 2000

Art Unit: 2814

For: SEMICONDUCTOR POWER MODULE  
HAVING AN ELECTRICALLY INSULATING  
HEAT SINK AND METHOD OF  
MANUFACTURING THE SAME

Examiner: D. P. NGUYEN

**AMENDMENT "K" AND RESPONSE TO OFFICIAL ACTION DATED JANUARY  
18, 2008 WITH REQUEST FOR CONTINUED EXAMINATION**

MS RCE  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

**INTRODUCTORY COMMENTS**

In response to the non-final official action dated January 18, 2008, the applicants respectfully request that the application be reconsidered in light of the following amendments and/or remarks.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks/Arguments** begin on page 4 of this paper.